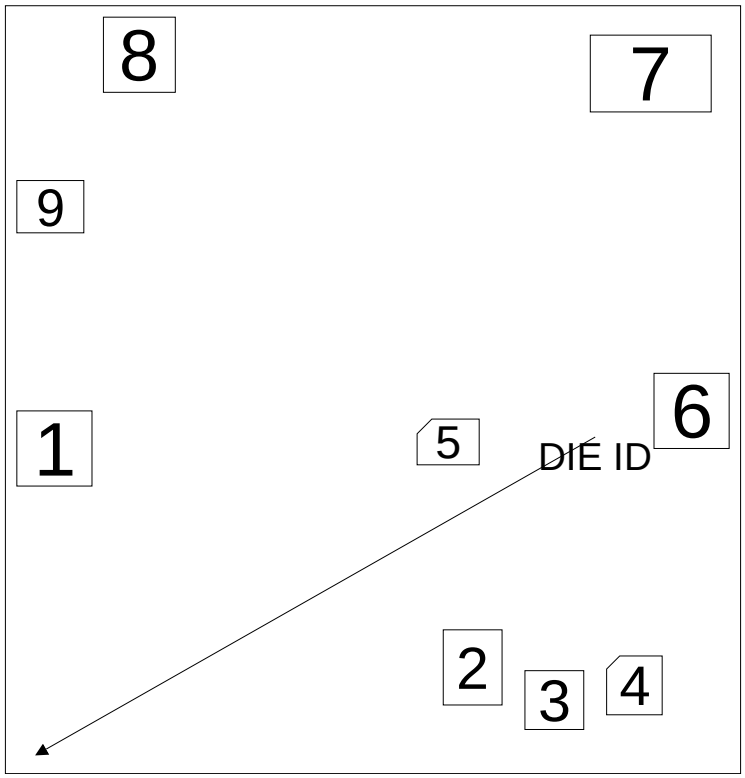
LM136-2.5 MDE MCD2600A
SMD#5962R0050102V9A
VOLTAGE REFERENCE DIODE

NOV 05, 2008

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM136BG-2.5	Bond Pad Opening Size (min)	111.76µm x 116.84µm
Die Step	B	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	Gold Back
Die Size (Drawn)	1143.0µm x 1193.8µm 45.0mils x 47.0mils	Back Side Connection	Floating or -
Thickness	254µm Nominal		
Min Pitch	626µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(B-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
ADJ	1	-495	-91	117	x	117
NC	2	155	-432	91	x	117
NC	3	282	-483	91	x	91
NC	4	406	-460	86	x	91
NC	5	117	-81	97	x	71
+	6	495	-33	117	x	117
NC	7	432	491	188	x	119
-	8	-363	521	112	x	117
NC	9	-502	284	104	x	81

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Notes

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